



04-29-02

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THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Hua Ji  
Title: HDP CVD Process For Void-Free Gap Fill Of A High Aspect Ratio Trench  
Application No.: 10/080,468 Filing Date: February 22, 2002  
Examiner: Unknown Group Art Unit: Unknown  
Docket No.: M-12589 US

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San Jose, California  
April 26, 2002  
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COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT  
UNDER 37 CFR § 1.97(b)

Dear Sir:

Pursuant to 37 C.F.R. § 1.56, § 1.97 and § 1.98, the documents listed on the accompanying form PTO-1449 are called to the attention of the Examiner for the above patent application. Copies of these documents are enclosed.

Citation of these documents shall not be construed as:

1. an admission that the documents are necessarily prior art with respect to the instant invention;
2. a representation that a search has been made; or
3. an admission that the information cited herein is, or is considered to be, material to patentability as defined in § 1.56(b).

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Respectfully submitted,

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